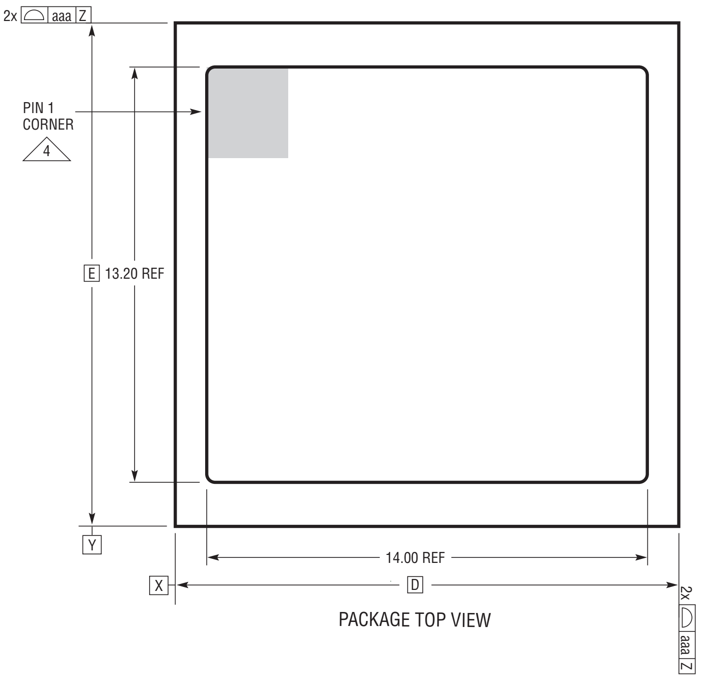
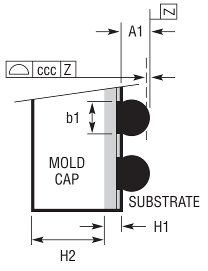
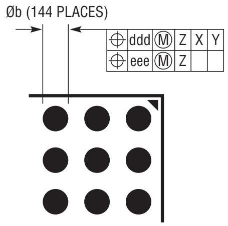
BGA Package
144-Lead (16mm × 16mm × 8.34mm)
(Reference LTC DWG # 05-08-7078 Rev A)



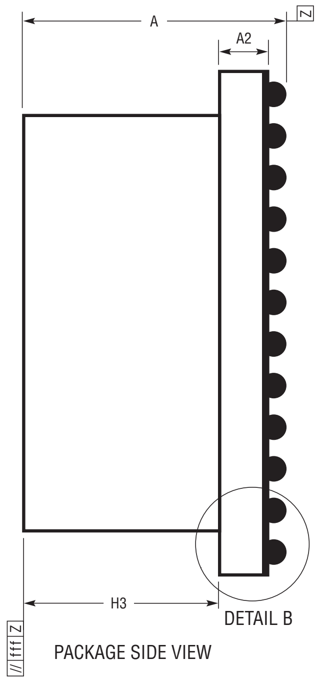
PACKAGE TOP VIEW



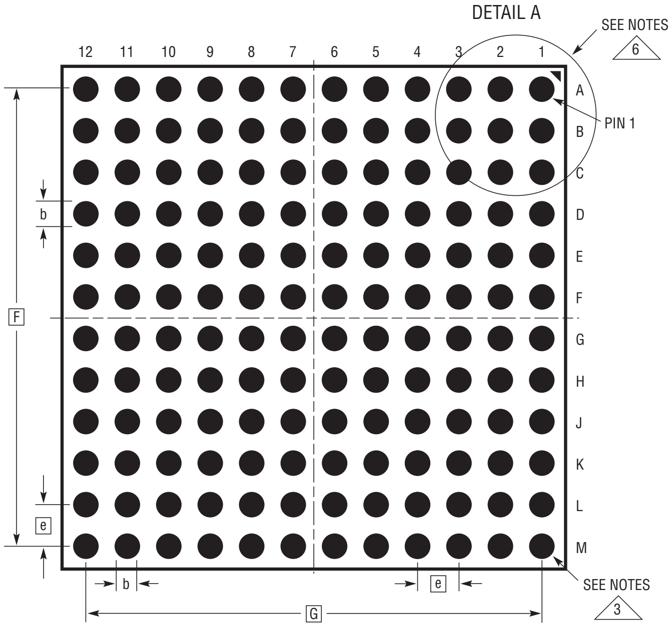
DETAIL B



DETAIL A



PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW

NOTES:

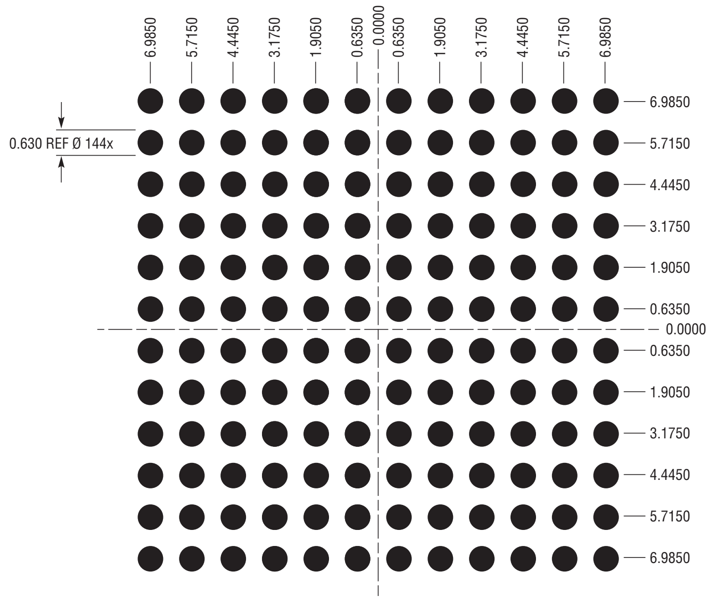
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS

3. BALL DESIGNATION PER JEP95

4. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

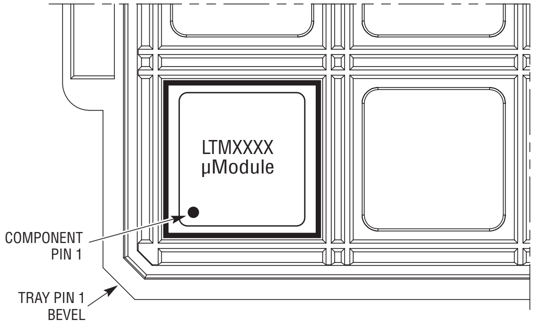


SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS

SYMBOL	MIN	NOM	MAX	NOTES
A	8.00	8.34	8.68	
A1	0.50	0.60	0.70	BALL HT
A2	1.74	1.84	1.94	
b	0.70	0.75	0.80	BALL DIMENSION
b1	0.60	0.63	0.66	PAD DIMENSION
D		16.00		
E		16.00		
e		1.27		
F		13.97		
G		13.97		
H1		0.34 REF		SUBSTRATE THK
H2		1.50 REF		MOLD CAP HT
H3	5.75	5.90	6.05	INDUCTOR HT
aaa			0.15	
ccc			0.20	
ddd			0.30	
eee			0.15	
fff			0.35	

TOTAL NUMBER OF BALLS: 144



PACKAGE IN TRAY LOADING ORIENTATION